

Amendment to the Claims:

This listing of Claims will replace all prior versions, listings of Claims in the application:

Listing of Claims:

1. (currently amended) A ~~non-vacuum~~ process for the fabrication of an electronic and opto-electronic device with an inverted device structure based on organic semiconductors comprising the steps of:

- forming a first low work function electrode layer on a conducting substrate using an electrodeposition technique ~~using non-vacuum processing techniques~~;
- forming at least one organic semiconductor material layer ~~using non-vacuum processing techniques~~; and
- forming a second high work function electrode layer ~~using non-vacuum processing techniques~~.

2. (cancelled)

3. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1 wherein said ~~non-vacuum processing techniques for forming said first electrode layer and said second electrode layer are independently selected from a group of electrochemical processing techniques including electroless deposition and electrodeposition. Said electroless deposition and electrodeposition may be carried out in either aqueous phase or organic phase.~~

4. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1 wherein ~~said non-vacuum processing techniques for forming said first electrode layer and said second~~ high work function electrode layer is formed using ~~are independently selected from a group of~~ solution processing techniques including ~~spin coating~~, thermal transfer printing, spray and screen printing.

5. (cancelled)

6. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1, wherein deposition of said first ~~and second electrode layers are~~ low work function electrode layer is performed in ~~a chamber~~ an electrodeposition unit, said electrodeposition unit being enclosed in a closed chamber containing an inert gas and a reduction agent.

7. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1, further comprising a step of ~~treating~~ post-deposition treatment on said first and second electrode layers in a reducing atmosphere in order to minimize contents of oxygen and water.

8. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1 wherein ~~said non-vacuum processing techniques for forming~~ said organic semiconductor layer ~~are selected from a group of solution processing techniques of~~ is formed using solution processing techniques including spin coating, screen printing, thermal transfer printing, spray and dip-coating.

9. (cancelled)

10. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1 further comprising a step of forming said device in a "layer to layer" mode by combining a first part and a second part. Said first part consisting of the first electrode coated with at least a layer of a first organic semiconductor material, said second part consisting of the second electrode coated with at least a layer of a second organic semiconductor material. Said first part and second part being constructed separately and assembled by aligning and sticking said first part onto said second part. And sticking of said first part to second part is achieved by cross-linking said first organic semiconductor layer and said second organic semiconductor layer with assistance of heating, light or electron radiation.

11. (currently amended) A ~~non-vacuum~~ process as defined in Claim 1, wherein said organic electronic and opto-electronic device with an inverted device structure being selected from a group of: organic light emitting diode, organic thin film transistor, organic solar cell, organic photodiode, organic memory chip, organic electronic circuit, and organic sensor.